

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): ~~Wafer~~ A wafer comprising a thermostable α -amylase present in an amount of 10 to 1000 units per gram of a final dough batter, at least one proteinase, at least one xylanase, sodium bicarbonate, an in-situ modified starch, and a humidity that is not greater than 6%.

Claim 2 (canceled):

Claim 3 (currently amended): ~~Wafer~~ The wafer according to ~~claim 1~~ Claim 1, wherein the wafer is selected from the group consisting of a flat wafer, a sugar wafer, and a three dimension shaped wafer.

Claims 4-5 (canceled):

Claim 6 (currently amended): ~~Wafer~~ The wafer according to ~~claim 1~~ Claim 1 comprising at least one component selected from the group consisting of gassing agents and gas generating microorganisms.

Claim 7 (currently amended): ~~Wafer~~ The wafer according to ~~claim 1~~ Claim 1, wherein the molecular weight of starch has been reduced.

Claim 8 (currently amended): ~~Wafer~~ The wafer according to ~~claim 1~~ Claim 1, wherein the α -amylase is of an origin selected from the group consisting of bacterial, fungal and plants origin.

Claim 9 (currently amended): ~~Process~~ A process for making a wafer comprising the steps of making a wafer batter or a dough by mixing at least flour, water, at least one proteinase, at least one xylanase, sodium bicarbonate, and a thermostable α -amylase present in an amount of 10 to 1000 units per gram of a final dough batter and baking it on at least one hot surface, the wafer having a humidity at the end of the baking step that is not greater than 6%.

Claims 10-12 (canceled):

Claim 13 (currently amended): ~~Process~~ The process according to ~~claim 9~~ Claim 9, wherein the wafer batter or dough comprises at least one component selected from the group consisting of gassing agents and gas generating microorganisms.

Claim 14 (currently amended): A method of using thermostable α -amylase to manipulate textural attributes of a wafer comprising the steps of adding α -amylase to a wafer batter having at least one proteinase, at least one xylanase and sodium bicarbonate and baking the wafer batter, the wafer having a humidity at the end of the baking step that is not greater than 6%, wherein the thermostable α -amylase is present in an amount of 10 to 1000 units per gram of a final dough batter.

Claim 15 (currently amended): The method of ~~claim~~ Claim 14, the wafer batter comprising at least a gassing agent.

Claim 16 (currently amended): ~~Method~~ A method for manufacturing a wafer comprising the steps of modifying a starch in a wafer batter having at least one proteinase, at least one xylanase and sodium bicarbonate without increasing batter viscosity by treating the batter with thermostable α -amylase, and baking the wafer batter, the wafer having a humidity at the end of the baking step that is not greater than 6%, wherein the thermostable α -amylase is present in an amount of 10 to 1000 units per gram of a final dough batter.

Claim 17 (currently amended): ~~Method~~ The method according to ~~claim 16~~ Claim 16, wherein the wafer batter does not stick to baking plates.

Claims 18-19 (canceled):

Claim 20 (currently amended): ~~Wafer~~ The wafer according to ~~claim 1~~ Claim 1, wherein soluble dextrans have been produced.